



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC750N10ND G		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000866714						
<b>Package</b>		PG-TDSON-8-4		<b>Weight*</b>		97.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.177	1.21	1.21	12088	12088
chip_2	inorganic material	silicon	7440-21-3	1.177	1.21	1.21	12088	12088
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.045	0.05		459	
wire	non noble metal	copper	7440-50-8	44.654	45.88	45.94	458678	459275
	non noble metal	aluminium	7429-90-5	0.274	0.28	0.28	2818	2818
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		925	
	plastics	epoxy resin	-	6.394	6.57		65680	
	inorganic material	silicondioxide	60676-86-0	38.545	39.59	46.25	395931	462536
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13432	13432
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	493	494
solder	non noble metal	tin	7440-31-5	0.073	0.07		745	
	noble metal	silver	7440-22-4	0.091	0.09		932	
	non noble metal	lead	7439-92-1	3.465	3.56	3.72	35592	37269
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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